

60V N-Channel Power Speed FET
• General Description

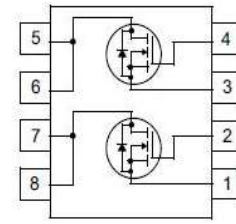
It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

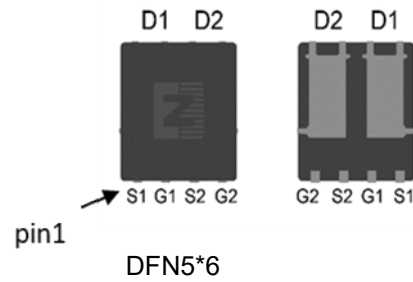
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- AEC-Q101 Qualified

• Application

- BLDC Motor driver
- DC-DC
- Battery protection

• Product Summary


$V_{DS} = 60V$
 $R_{DS(ON)} = 7.6m\Omega$
 $I_D = 52A$


• Ordering Information:

Part NO.	ZMDA68608N
Marking	ZMD68608
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_C=25^\circ C$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		60	V
Gate-Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ C$	52	A
	I_D	$T_C=75^\circ C$	42	A
	I_D	$T_C=100^\circ C$	37	A
Pulsed Drain Current ^①	I_{DM}	Pulsed; $t_p \leq 10 \mu s$; $T_{mb} = 25^\circ C$;	208	A
Total Power Dissipation	P_D	$T_C=25^\circ C$	52	W
Total Power Dissipation	P_D	$T_A=25^\circ C$	3.0	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ C$
Storage Temperature	T_{STG}		-55 to +175	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	L=0.1mH, VGS=10V, Rg=25 Ω ,	12	mJ
		L=0.5mH, VGS=10V, Rg=25 Ω ,	21	mJ
ESD Level (HBM)			CLASS 2	

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	2.9	°C/W
Thermal resistance, junction-ambient	$R_{thJA\oplus}$		-	50	°C/W
Soldering temperature (total time<10s)	Tsold		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2	2.6	4	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=60V$	-	-	1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=14A$	-	7.6	9.5	m Ω
Forward Transconductance	g_{FS}	$V_{GS}=5V, I_{SD}=5A$	-	14	-	S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=14A$	-	-	1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=25V$	-	1196	-	pF
Output capacitance	C_{oss}		-	661	-	
Reverse transfer capacitance	C_{rss}		-	47	-	
Gate Resistance	R_g	$f=1MHz$	-	1.2	-	Ω
Total gate charge	Q_g	$V_{DD}=30V, I_D=14A, V_{GS}=10V$	-	19	-	nC
Gate - Source charge	Q_{gs}		-	4.9	-	
Gate - Drain charge	Q_{gd}		-	5.5	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V, R_G=3.3\Omega, I_D=20A$	-	6	-	ns
Turn-ON Rise time	t_r		-	4	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	11	-	ns
Turn-Off Fall time	t_f		-	7	-	ns
Reverse Recovery Time	t_{rr}	$V_{DD}=20V, dI_S/dt=100A/\mu s, I_S=20A$	-	26	-	ns
Reverse Recovery Charge	Q_{rr}		-	16	-	nC

Fig.1 Gate-Charge Characteristics

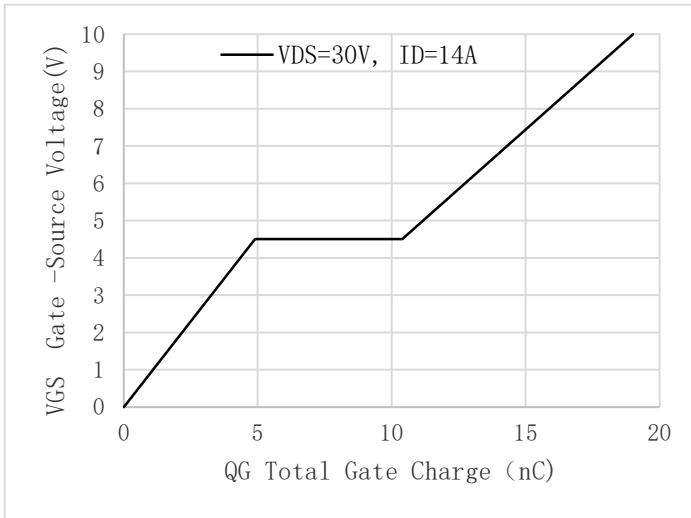


Fig.2 Capacitance Characteristics

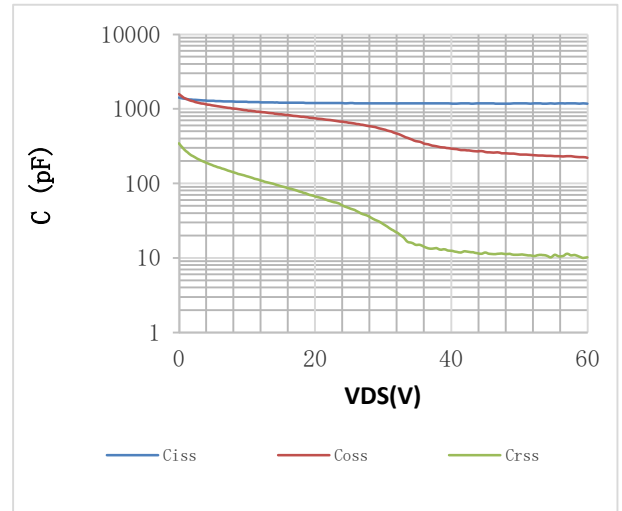


Fig.3 Power Dissipation

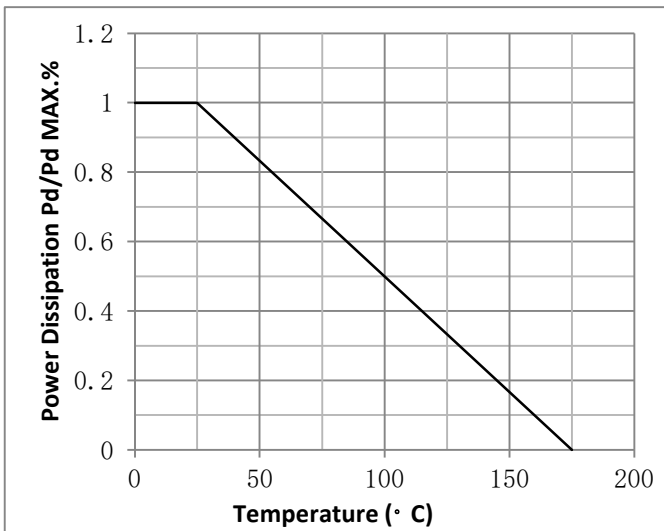


Fig.4 Typical output Characteristics

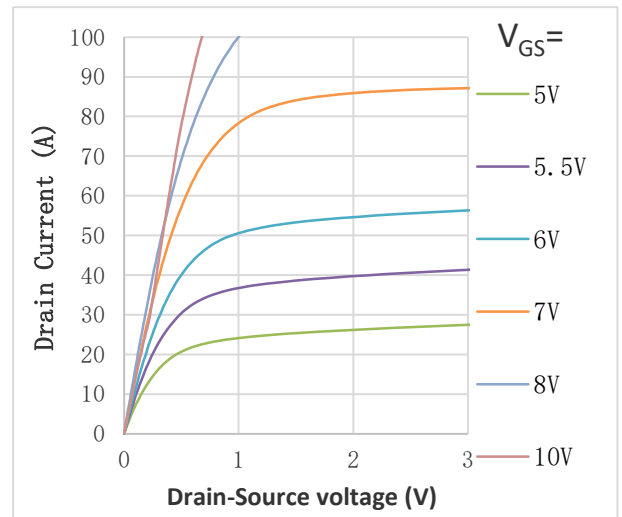


Fig.5 Threshold Voltage V.S Junction Temperature

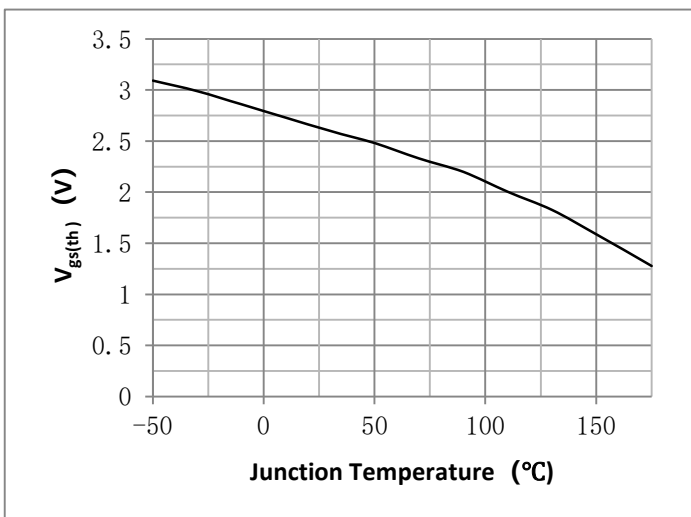


Fig.6 Resistance V.S Drain Current

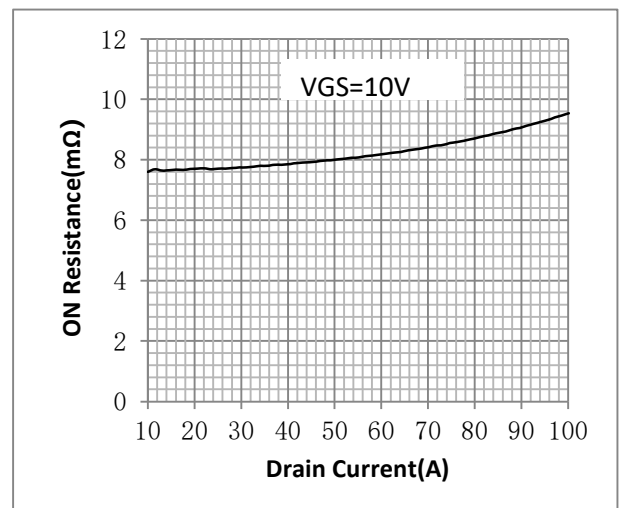


Fig.7 On-Resistance VS Gate Source Voltage

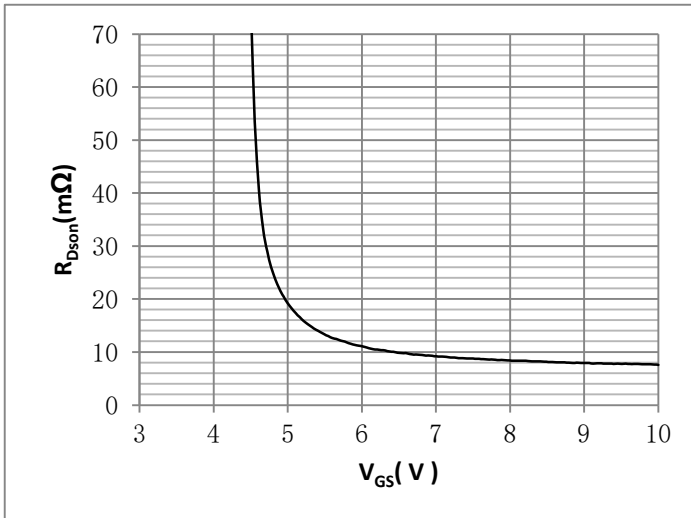


Fig.8 On-Resistance V.S Junction Temperature

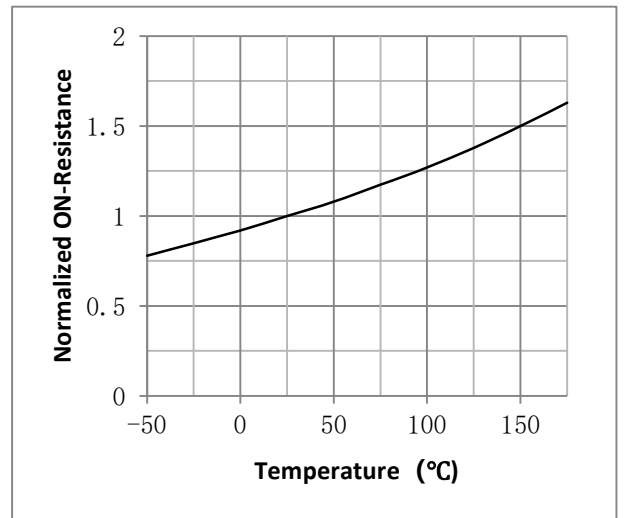


Figure 9. Diode Forward Voltage vs. Current

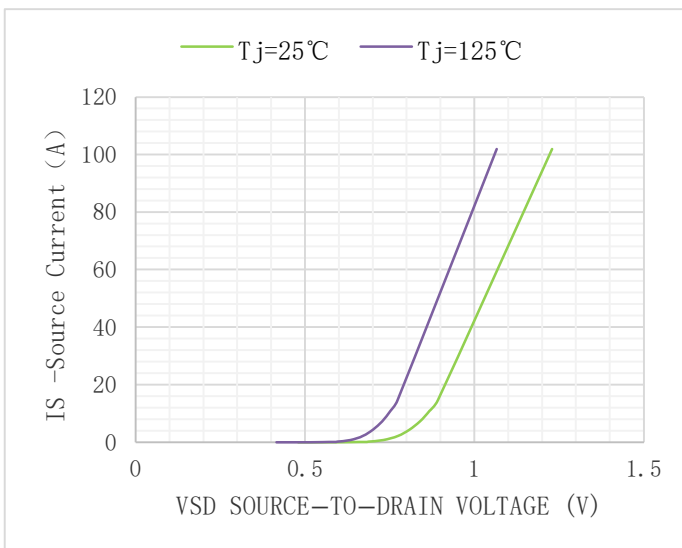


Figure 10. Transfer Characteristics

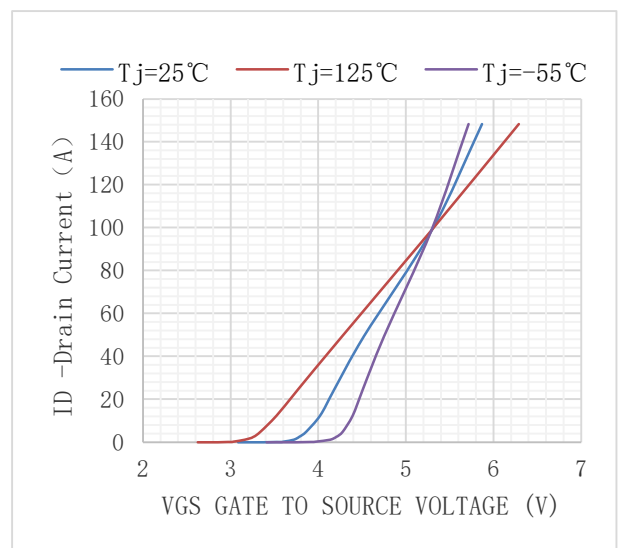


Fig.11 SOA Maximum Safe Operating Area

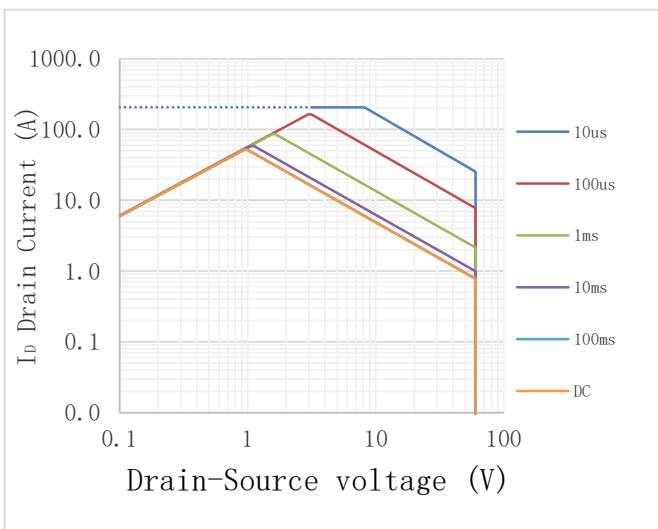
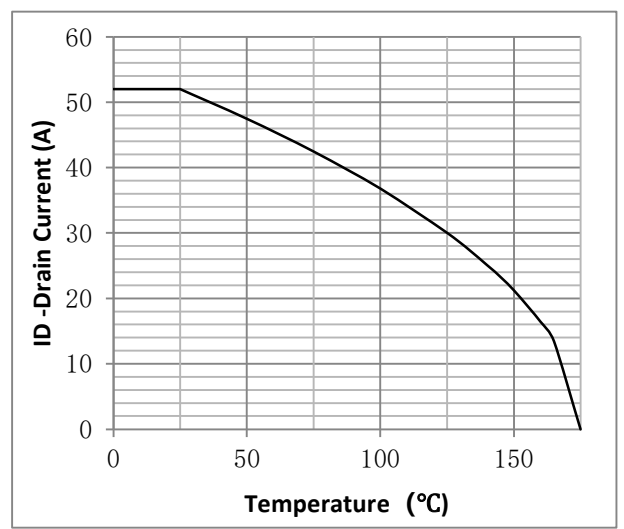
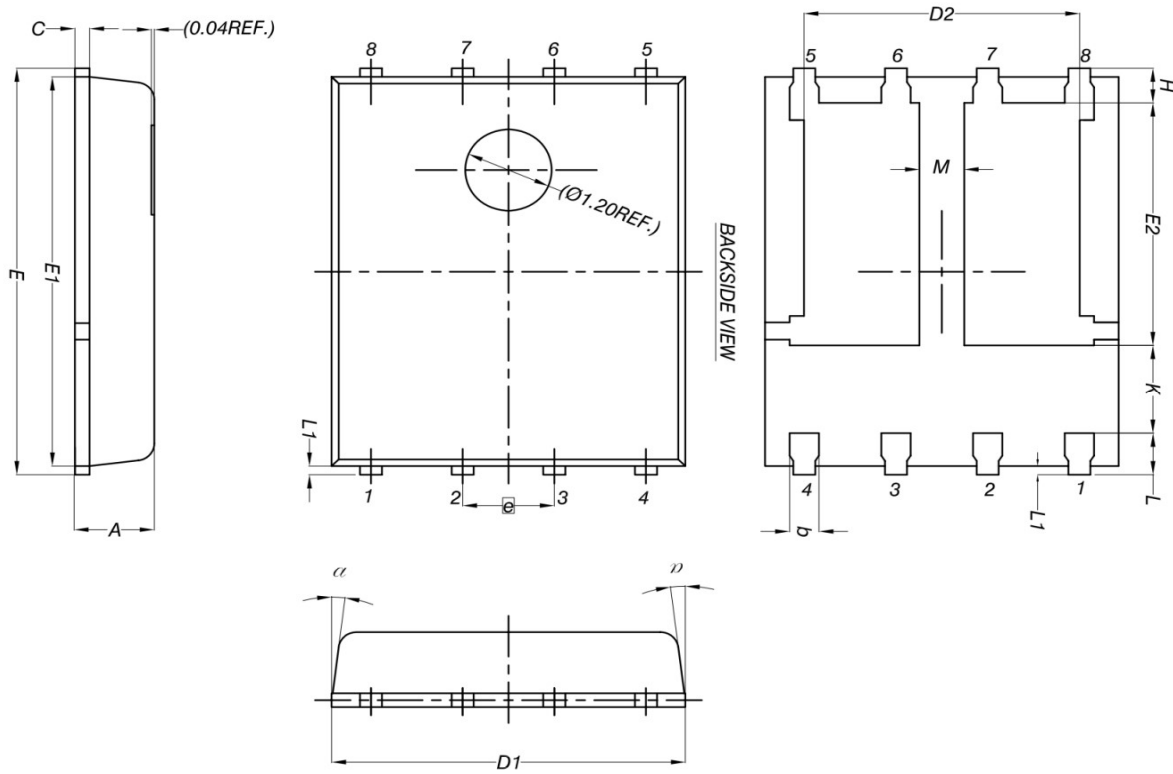


Fig.12 I_D vs. Case Temperature^③

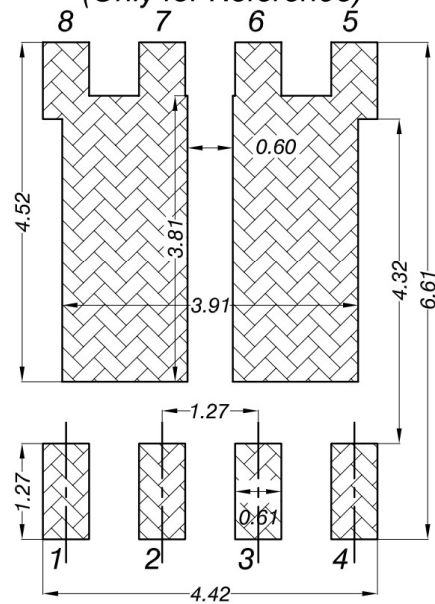


•DFN5*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	-	-
α	0°	-	12°

Land Pattern
(Only for Reference)



Note:

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=+20V/-10V$, $T_j=175^{\circ}C$, $t=1000$ hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature.
 $V_{GS}=10V$.

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Revision History

Version	Date	Change
A	2024.12.19	New